

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A semiconductor device package comprising:
an electrical connector formed of an electrically and thermally conductive material including a web portion and a conductive post leg extending from an edge of said web portion said leg including a free surface, said web portion and said conductive post leg forming a unitary body, said web portion and said conductive leg each including an inner surface and an outer surface opposite said inner surface; and
a semiconductor die having a first power contact on a first major surface thereof and a second power contact and a control contact on a second major surface thereof opposite to said first power contact, said first power contact being electrically connected to said inner surface of said web portion by a conductive adhesive and spaced from said inner surface of said conductive leg; and
mold compound disposed over at least said outer surface of said web portion and said outer surface of said conductive leg;
wherein said conductive post leg is located opposite an edge of said die and extends at least between said first power contact and said second power contact and said free surface faces a same direction as said second major surface of said semiconductor die.

Claim 2 (Canceled)

3. (Original) A semiconductor device package according to claim 1, wherein said semiconductor die is a MOSFET.

4. (Currently Amended) A semiconductor device package according to claim 1, further comprising a second conductive post leg extending from another edge of said web portion opposite said conductive leg.

5. (Original) A semiconductor device package according to claim 1, wherein said first power contact is a drain contact of a MOSFET.

6. (Original) A semiconductor device package according to claim 1, wherein said first power contact is electrically connected to said web portion by a layer of solder.

7. (Currently Amended) A semiconductor device package comprising:
~~an electrical connector formed of an~~ electrically and thermally conductive material
~~including a web portion, a rim extending around said web portion, and a first post extending from~~
~~an edge of said rim, said web portion, said rim and said first conductive post forming a unitary~~
~~body~~ cup-shaped clip including an interior web surface; and

a semiconductor die having a first power contact on a first major surface thereof and a second power contact on a second major surface thereof opposite to said first power contact, said first power contact being electrically connected to said interior web portion surface by a conductive adhesive[[;]]

~~wherein said rim is located opposite an edge of said die.~~

8. (Original) A semiconductor device package according to claim 1, further comprising a control contact formed on said second major surface of said semiconductor die.

9. (Original) A semiconductor device package according to claim 1, wherein said semiconductor die is a MOSFET.

10. (Original) A semiconductor device package according to claim 1, further comprising a second conductive post disposed on an edge of said rim opposite said first conductive post.

11. (Original) A semiconductor device package according to claim 1, wherein said first power contact is a drain contact of a MOSFET.

12. (Original) A semiconductor device package according to claim 1, wherein said first power contact is electrically connected to said web portion by a layer of solder.

13. (Currently Amended) A semiconductor device package comprising a semiconductor device die having parallel top and bottom surfaces; said top surface having a first planar metallic electrode, said bottom surface having a ~~solderable~~ second planar ~~metal~~ metallic electrode; ~~at least one solderable conductive layer formed on at least a first portion of said first planar metallic electrode, said at least one solderable conductive layer having an upper planar surface;~~ a metal clip having a flat web portion and at least one peripheral rim portion extending from an edge of said flat web portion; said bottom surface of said web being electrically connected in surface to surface contact to said ~~solderable~~ second planar ~~metal~~ metallic electrode on the bottom surface of said die by a conductive adhesive; said peripheral rim portion of said clip being extended over and spaced from an edge of said die and including a projection terminating in a ~~clip rim~~ projection surface which is in plane parallel to the plane of said ~~upper first planar surface of said at least one solderable conductive layer and being insulated therefrom~~ metallic electrode, wherein said rim portion and said web portion are integral and form a unitary body, said clip is a cup-shaped structure, said peripheral rim is a continuous rim surrounding and spaced from the exterior of said die, ~~wherein~~ and said metal clip serves as an electrical connector for electrical connection to said ~~solderable~~ second planar metal electrode.

14. (Currently Amended) The package of claim 13 which further includes a ~~second~~ third planar metallic electrode on said top surface of said die, said ~~second~~ third metallic electrode comprising a control electrode; ~~and a second solderable planar metal electrode having an upper surface which is coplanar with said upper surface of said at least one solderable planar metal electrode.~~

15. (Currently Amended) The device of claim 13, wherein said ~~at least one solderable~~ second planar ~~metal~~ metallic electrode includes a nickel layer ~~connected to said metallic electrode~~ and an easily solderable metal connected atop said nickel layer.

16. (Currently Amended) The device of claim 13, ~~which further includes a~~
~~conductive epoxy connecting said bottom surface of said web to said bottom surface of said die~~
wherein said conductive adhesive is comprised of a conductive epoxy.

17. (Currently Amended) The device of claim 14, ~~which further includes a~~
~~conductive epoxy connecting said bottom surface of said web to said bottom surface of said die~~
wherein said conductive adhesive is comprised of a conductive epoxy.

Claims 18 - 24 (Canceled)

25. (Currently Amended) A semiconductor device package comprising a semiconductor device die having parallel top and bottom surfaces; said top surface having a first planar metallic electrode, said bottom surface having a ~~solderable~~ second planar metal metallic electrode; at least one solderable ~~conductive layer formed body~~ on at least a first portion of said first planar metallic electrode, said at least one solderable ~~conductive layer body~~ having an upper planar surface; a metal clip having a flat web portion and at least one peripheral rim portion extending from an edge of said flat web portion; said bottom surface of said web being electrically connected in ~~surface-to-surface contact~~ to said ~~solderable~~ second planar metal metallic electrode on the bottom surface of said die by a conductive adhesive; said peripheral rim portion of said clip being extended over and spaced from an edge of said die and including at least one projection terminating in a ~~clip rim projection~~ surface which is in plane parallel to the plane of said upper planar surface of said at least one solderable ~~conductive layer body~~ and being insulated therefrom, wherein said rim portion and said web portion are integral and form a unitary body, said clip is a cup-shaped structure, said peripheral rim is a continuous rim surrounding and spaced from the exterior of said die, ~~a conductive epoxy connects said bottom surface of said web to said solderable planar metal electrode, wherein~~ and said metal clip serves as an electrical connector for electrical connection to said solderable planar ~~metal~~ metallic electrode.

26. (New) A semiconductor device package according to claim 1, wherein said web portion further includes at least one mold lock.

27. (New) A semiconductor device package according to claim 1, wherein mold compound further resides in a space between said inner surface of said conductive leg and said semiconductor die.

28. (New) A semiconductor device package according to claim 1, further comprising another conductive leg extending from said edge of said web portion.

29. (New) A semiconductor device package according to claim 28, wherein said another conductive leg further includes an interior surface opposite and spaced from said die, wherein said mold compound resides between said interior surfaces of said conductive legs and said semiconductor die.

30. (New) A semiconductor device package according to claim 1, wherein mold compound extends to said outer surface of said conductive leg.

31. (New) A semiconductor device package according to claim 1, further comprising at least one solderable contact post connected to said second power electrode.

32. (New) A semiconductor device package according to claim 31, wherein said conductive leg includes a free surface which is coplanar with said solderable contact post.

33. A semiconductor device package according to claim 1, further comprising at least one solderable contact post connected to said control electrode.

34. (New) A semiconductor device package according to claim 33, wherein said conductive leg includes a free surface which is coplanar with said solderable contact post.

35. (New) A semiconductor device package according to claim 7, wherein said cup-shaped clip further includes at least one projecting having a projection surface facing a same direction as said second power electrode.

36. (New) A semiconductor device package according to claim 7, wherein said second power contact is solderable.

37. (New) A semiconductor device package according to claim 35, further comprising another projection having a projection surface, said another projection being disposed opposite said projection.

38. (New) A semiconductor device package according to claim 35, further comprising a plurality of spaced projections disposed at said one side of said clip.

39. (New) A semiconductor device package according to claim 38, further comprising another plurality of spaced projections disposed opposite said plurality of spaced projections.

40. (New) A semiconductor device according to claim 7, wherein said cup-shaped clip is silver-plated.

41. (New) A semiconductor device according to claim 7, wherein said conductive adhesive is comprised of silver-loaded epoxy.